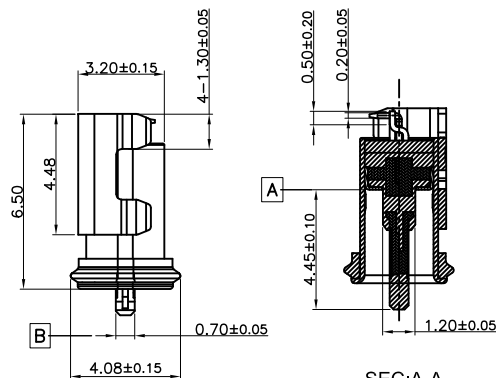
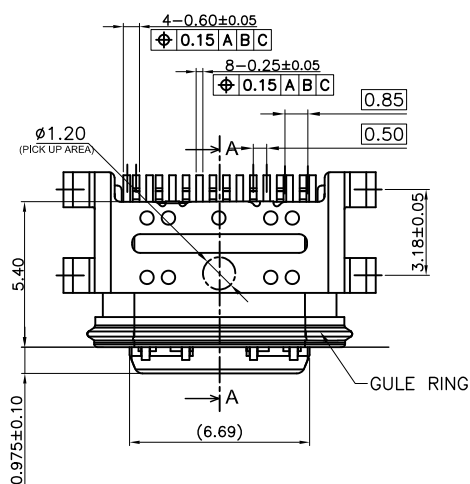
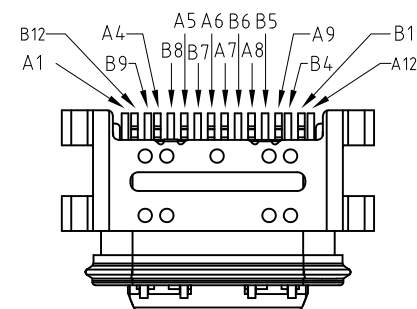


3D VIEW



SEC:A-A



NOTES:

1.MATERIAL SPECIFICATION:

- 1-1.HOUSING:High-Temp Plastics,UL94V-0,Color:Black.
- 1-2.CONTACTS:Copper Alloy T=0.20mm.
- 1-3.OUTER SHELL:Stainless Steel,T=0.30mm.
- 1-4.INNER SHELL:Stainless Steel,T=0.20mm.
- 1-5.MID-PLATE:Stainless Steel,T=0.20mm.
- 1-6.SOLDER-PLATE:Stainless Steel,T=0.10mm.

2.PLATING SPECIFICATION:

2-1.CONTACTS:

- Ni UNDERPLATED OVER ALL;
3u" Au +3u" Pd Min Plating On Contact Area;
3u" Au Plating On Solder Area.

2-2.SHELL:

- Ni UNDERPLATED OVER ALL;
Gold Flash Plated On Solder Leg.

3.RoHS AND HF COMPLIANT.

4.MECHANICAL PERFORMANCE:

- 4-1.MATING FORCE:6~20N(Initial);5~20N(After)
- 4-2.UNMATING FORCE:8~20N(Initial);6~20N(After)
- 4-3.DURABILITY:10000 CYCLES.

5.ELECTRICAL PERFORMANCE:

- 5-1.CURRENT RATING:3A;VOLTAGE RATING:5.0V
- 5-2.LLCR:

- VBUS & GND PINS:40mΩH/PIN MAX.;
OTHERS PINS:40mΩH/PIN MAX.;
LLCR MAX. CHANGE OF ALL PINS:20mΩ.

5-3.INSULATION RESISTANCE:100MΩ MIN.

- 5-4.DIELECTRIC WITHSTANDING VOLTAGE:
100V AC FOR 1 MINUTE.

6.ENVIROMENTAL PERFORMANCE:

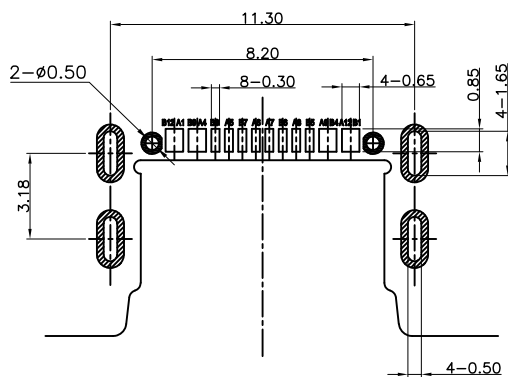
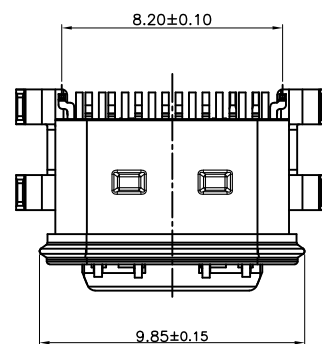
- OPERATING TEMPERATURE:-20℃~+85℃.

7.RECOMMENDED PROCESS:

- THE PEAK TEMPERATURE ON THE BOARD
SHALL MAINTAIN 10±1 SECONDS AT 255±5℃.

Pin Assignments

Contact Number	Signal Name	Contact Number	Signal Name
A1	GND	B12	GND
A4	VBUS	B9	VBUS
A5	CC1	B8	SBU2
A6	Dp1	B7	Dn2
A7	Dn1	B6	Dp2
A8	SBU1	B5	CC2
A9	VBUS	B4	VBUS
A12	GND	B1	GND

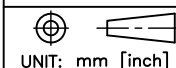
RECOMMENDED PCB LAYOUT
TOLERANCE:±0.05

深圳市华宇创精密电子有限公司

TOLERANCE:

X.X ±0.30
X.XX ±0.25
X.XXX ±0.15

X' ±2" X.X' ±0.5"



UNIT: mm [inch]

SCALE:1:1 SIZE: A4

DRAWN BY :

陈一鸣

DATE :

2014-02-23

PART NAME:

USB TYPE C 防水母座16P 沉板路舌 CH=0.35mm 带防水胶圈

CHECKED BY:

马跃

DATE :

2014-02-23

APPROVED BY:

邱敏

DATE :

2014-02-23

PART NO.

HYCW607-USBC16-200B

MOLD NO.

DRAW NO:

HYC-2412031054

SHEET NO.

1 OF 1